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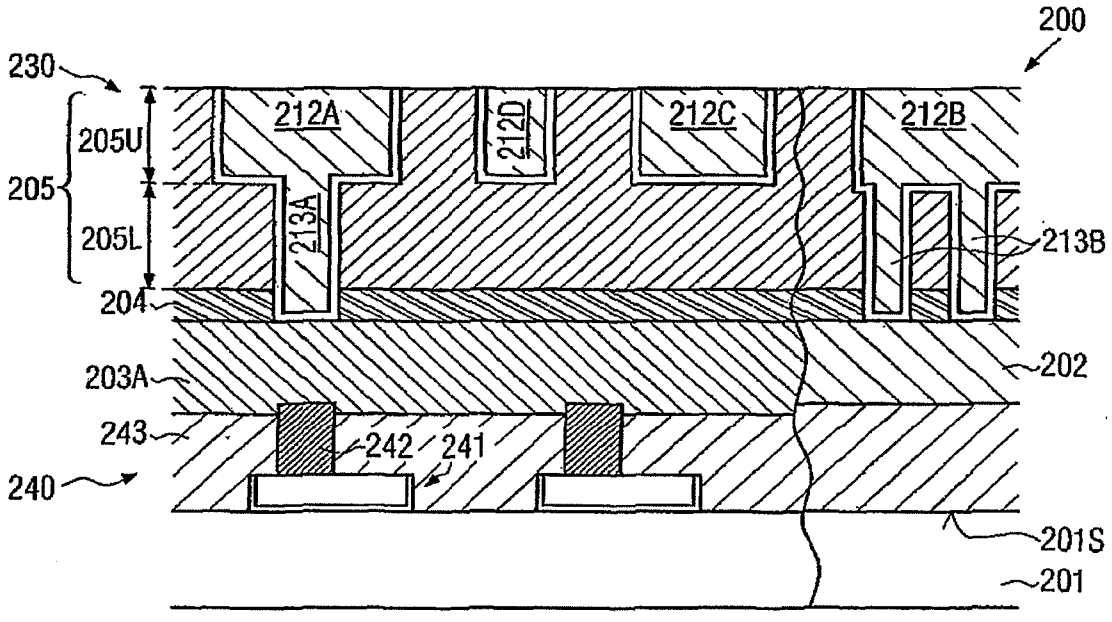
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(54) Title: A TECHNIQUE FOR INCREASING ADHESION OF METALLIZATION LAYERS BY PROVIDING DUMMY VIAS



(57) Abstract: By providing dummy vias (213B, 313B) below electrically non-functional metal regions (212B, 312B), the risk for metal delamination in subsequent processes may be significantly reduced. Moreover, in some embodiments, the mechanical strength of the resulting metallization layers (330) may be even more enhanced by providing dummy metal regions (303B), which may act as anchors for an overlying non-functional metal region (312B). In addition, dummy vias (213B, 313B) may also be provided in combination with electrically functional metal lines (212A, 212C, 212D, 312A) and regions (220A, 320A), thereby also enhancing the mechanical stability and the electrical performance thereof.

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